



Final Product Change Notification

202204015F01 : MCF5282 and MCF5216 Fab Site Expansion from TSMC3 to NXP-CHD

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 01, 2022 **Effective date:** Nov 30, 2022

Management summary

Wafer Fabrication site expansion for the MCF5282 and MCF5216 from Fab 3(TSMC3),Taiwan Wafer Fabrication site to the NXP CHD Fab Chandler, Arizona Wafer Fabrication site.

Change Category

- | | | | | |
|--|--|--|--|---|
| <input type="checkbox"/> Wafer
Fab
Process | <input type="checkbox"/> Assembly
Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test
Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer
Fab
Materials | <input type="checkbox"/> Assembly
Materials | <input type="checkbox"/> Mechanical
Specification | <input type="checkbox"/> Test
Equipment | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer
Fab
Location | <input type="checkbox"/> Assembly
Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test
Location | <input type="checkbox"/> Electrical
spec./Test
coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

NXP Semiconductors announces the Wafer Fabrication site expansion for the MCF5282 and MCF5216 associated with this notification, from the current Taiwan Semiconductor Manufacturing Company Fab 3(TSMC3),Taiwan Wafer Fabrication site to the NXP CHD Fab Chandler, Arizona Wafer Fabrication site.

Wafer Fabrication site expansion was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason

Qualification of NXP CHD Fab Chandler, Arizona is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking

The mask marking for CHD will reflect 0N04K, while the mask marking for TSMC3 will remain 2L95M

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Nov 27, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Fab Expansion. No Depletion of Inventory required.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 01, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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